

## SNx4AHCT08 Quadruple 2-Input Positive-AND Gates

### 1 Features

- Inputs are TTL-voltage compatible
- Latch-up performance exceeds 250 mA per JESD 17
- ESD protection exceeds JESD 22:
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- On products compliant to MIL-PRF-38535, All parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

### 2 Applications

- [Servers](#)
- [Network switches](#)
- [PCs and notebooks](#)
- [Electronic points-of-sale](#)

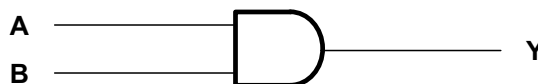
### 3 Description

The SNx4AHCT08 devices are quadruple 2-input positive-AND gates. These devices perform the Boolean function  $Y = A \times B$  or  $Y = \overline{\overline{A} + \overline{B}}$  in positive logic.

#### Package Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SNx4AHCT08	D (SOIC, 14)	8.65 mm × 3.91 mm
	DB (SSOP, 14)	6.20 mm × 5.30 mm
	NS (SOP, 14)	12.60 mm × 5.30 mm
	PW (TSSOP, 14)	5.00 mm × 4.40 mm
	RGY (VQFN, 14)	3.50 mm × 3.50 mm
	J (CDIP, 14)	19.56 mm × 6.67 mm
	W (CFP, 14)	9.21 mm × 5.97 mm
	DGV (TVSOP, 14)	3.60 mm × 4.40 mm
	N (PDIP, 14)	19.30 mm × 6.35 mm
	FK (LCCC, 20)	8.89 mm × 8.89 mm
BQA (WQFN, 14)	3.00 mm × 2.50 mm	

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic



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## 4 Revision History

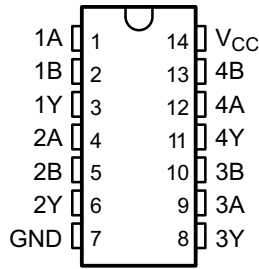
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision O (May 2023) to Revision P (October 2023)</b>	<b>Page</b>
<ul style="list-style-type: none"> <li>Updated R<math>\theta</math>JA values: D = 97.5 to 124.5; Updated D package for R<math>\theta</math>JC(top), R<math>\theta</math>JB, <math>\Psi</math>JT, <math>\Psi</math>JB, and R<math>\theta</math>JC(bot), all values in °C/W .....</li> </ul>	6

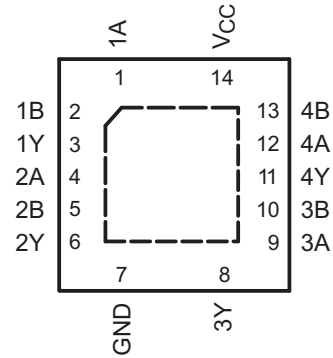
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<b>Changes from Revision N (September 2015) to Revision O (May 2023)</b>	<b>Page</b>
<ul style="list-style-type: none"> <li>Updated the numbering format for tables, figures, and cross-references throughout the document.....</li> <li>Updated the <i>package information</i> table to include BQA (WQFN).....</li> <li>Added BQA (WQFN) information to the <i>Thermal Information</i> table.....</li> </ul>	1 1 6

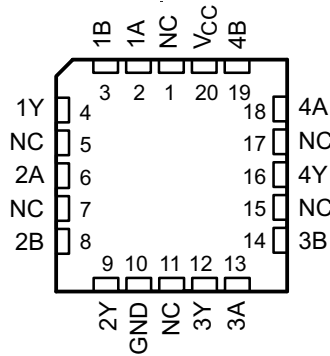
## 5 Pin Configuration and Functions



**Figure 5-1. SN54AHCT08 J or W Package, 14-Pin CDIP or CFP  
SN74AHCT08 D, DB, DGV, N, NS, or PW Package, 14-Pin SOIC, SSOP, TVSOP, PDIP, SO, or TSSOP (Top View)**



**Figure 5-2. SN74AHCT08 RGY or BQA Package, 14-Pin VQFN or WQFN (Top View)**



NC – No internal connection

**Figure 5-3. SN54AHCT08 FK Package, 20-Pin LCCC (Top View)**

**Table 5-1. Pin Functions**

NAME	PIN				TYPE (1)	DESCRIPTION
	SN74AHCT08		SN54AHCT08			
	D, DB, DGV, N, NS, PW	RGY, BQA	J, W	FK		
1A	1	1	1	2	I	1A Input
1B	2	2	2	3	I	1B Input
1Y	3	3	3	4	O	1Y Output
2A	4	4	4	6	I	2A Input
2B	5	5	5	8	I	2B Input
2Y	6	6	6	9	O	2Y Output
3Y	8	8	8	12	O	3Y Output
3A	9	9	9	13	I	3A Input
3B	10	10	10	14	I	3B Input
4Y	11	11	11	16	O	4Y Output
4A	12	12	12	18	I	4A Input
4B	13	13	13	19	I	4B Input
GND	7	7	7	10	—	Ground Pin

**Table 5-1. Pin Functions (continued)**

NAME	PIN				TYPE (1)	DESCRIPTION
	SN74AHCT08		SN54AHCT08			
	D, DB, DGV, N, NS, PW	RGY, BQA	J, W	FK		
NC	—	—	—	1	—	No Connection
				5		
				7		
				11		
				15		
				17		
V <sub>CC</sub>	14	14	14	20	—	Power Pin

(1) I = input, O = output

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	7	V
V <sub>O</sub>	Output voltage range <sup>(2)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub>	±20	mA
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>CC</sub>	±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature range	-65	150	°C
T <sub>J</sub>	Junction temperature		150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	
		±2000	
		±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		SN54AHCT08		SN74AHCT08		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.5	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		-8		-8	mA
I <sub>OL</sub>	Low-level output current		8		8	mA
Δt/Δv	Input transition rise or fall rate		20		20	ns/V
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	125	°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI Application Report, *Implications of Slow or Floating CMOS Inputs*, (SCBA004).

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SNx4AHCT08					UNIT	
	D (SOIC)	DB (SSOP)	DGV (TVSOP)	N (PDIP)	BQA (WQFN)		
	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS		
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	124.5	109.5	133.3	59.7	88.3	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	78.8	62.1	55.6	47.3	90.9	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	81	56.9	66.3	39.5	56.8	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	37	22.6	7.8	32.4	9.9	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	80.6	56.3	56.6	39.4	56.7	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, (SPRA953).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHCT08		SN74AHCT08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I <sub>OH</sub> = -8 mA		3.94			3.8		3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V			0.1			0.1	V	
	I <sub>OL</sub> = 8 mA				0.36		0.44	0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1 <sup>(1)</sup>	±1	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			2		20	20	μA	
ΔI <sub>CC</sub> <sup>(2)</sup>	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	1.5	mA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10			10	pF	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

(2) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 6.6 Switching Characteristics, V<sub>CC</sub> = 5 V ± 0.5 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 7-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54AHCT08		SN74AHCT08		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 15 pF	5 <sup>(1)</sup>	6.9 <sup>(1)</sup>		1 <sup>(1)</sup>	8 <sup>(1)</sup>	1	8	ns
t <sub>PHL</sub>				5 <sup>(1)</sup>	6.9 <sup>(1)</sup>		1 <sup>(1)</sup>	8 <sup>(1)</sup>	1	8	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF	5.5	7.9		1	9	1	9	ns
t <sub>PHL</sub>				5.5	7.9		1	9	1	9	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

### 6.7 Noise Characteristics

$V_{CC} = 5\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$ <sup>(1)</sup>

PARAMETER		SN74AHCT08			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.4	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		-0.4	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$	4.4			V
$V_{IH(D)}$	High-level dynamic input voltage	2			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.8	V

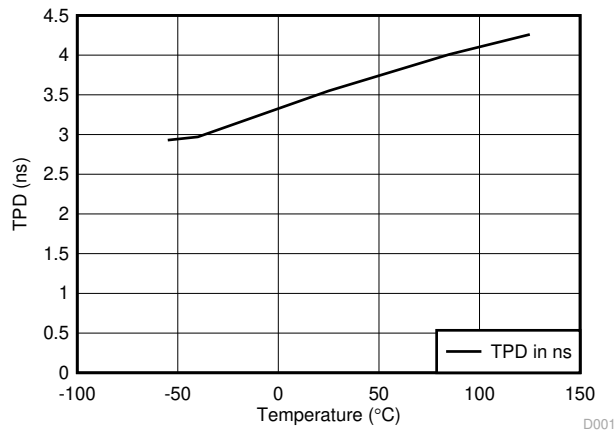
(1) Characteristics are for surface-mount packages only.

### 6.8 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

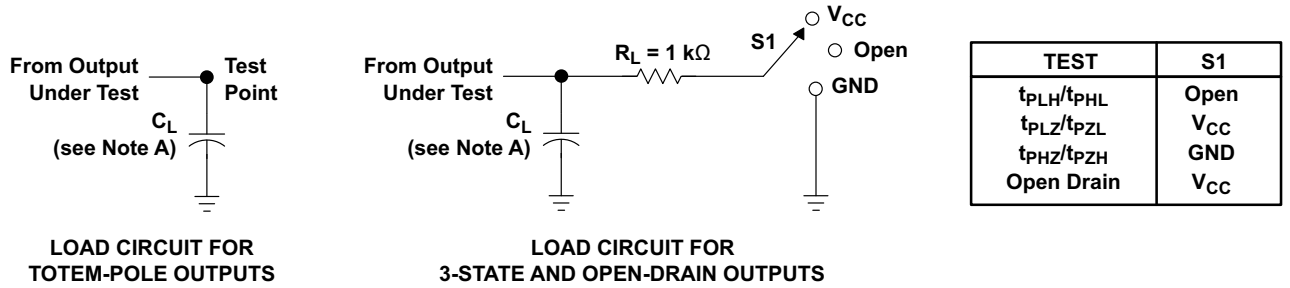
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$	No load, $f = 1\text{ MHz}$	18	pF

### 6.9 Typical Characteristics



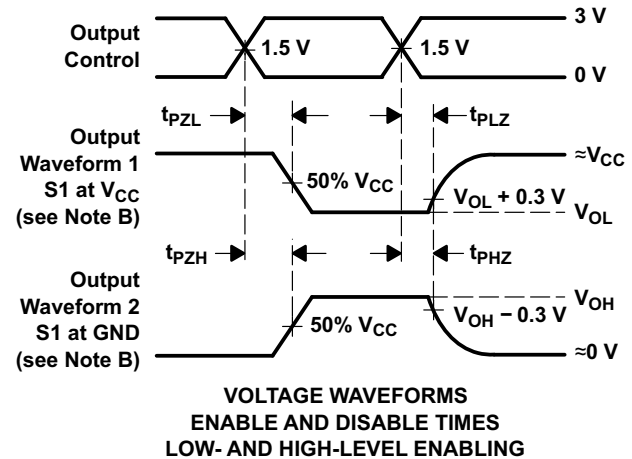
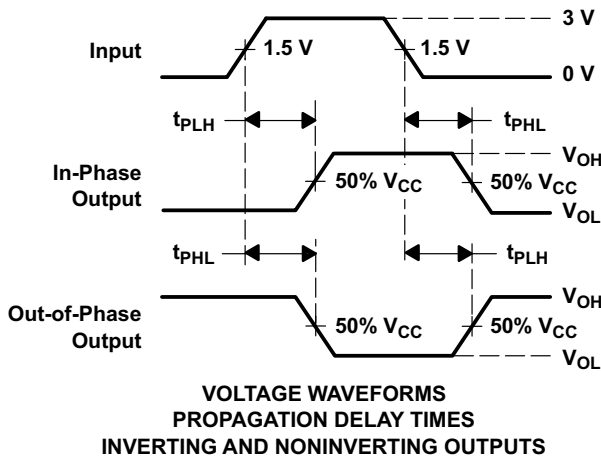
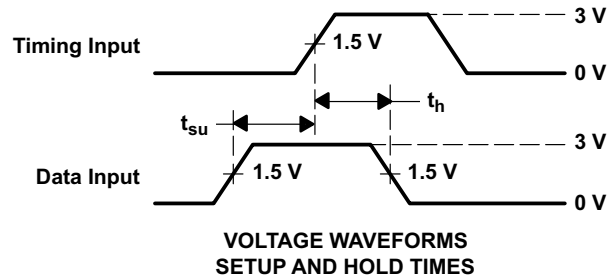
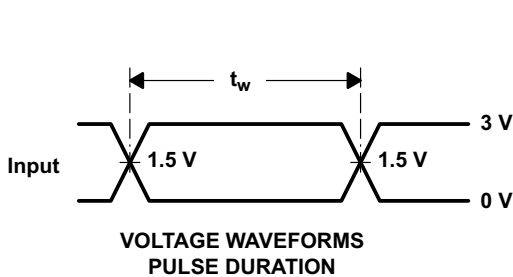
**Figure 6-1. TPD vs Temperature**

## 7 Parameter Measurement Information



LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.  
 D. The outputs are measured one at a time with one input transition per measurement.  
 E. All parameters and waveforms are not applicable to all devices.

Figure 7-1. Load Circuit and Voltage Waveforms

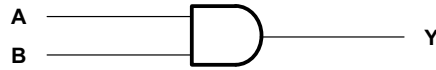


## 8 Detailed Description

### 8.1 Overview

The SNx4AHCT08 devices are quadruple 2-input positive-AND gates with low drive that will produce slow rise and fall times. This slow transition reduces ringing on the output signal. The device has TTL inputs that allow up translation from 3.3 V to 5 V. The inputs are high impedance when  $V_{CC} = 0$  V.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

- Slow rise and fall time on outputs allow for low-noise outputs
- TTL inputs allow up translation from 3.3 V to 5 V

### 8.4 Device Functional Modes

Table 8-1 is the function table for the SNx4AHCT08.

**Table 8-1. Function Table  
(Each Gate)**

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

## 9 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

The SNx4AHCT08 devices are low-drive CMOS devices that can be used for a multitude of bus-interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The TTL inputs can accept voltages down to 3.3 V and translate up to 5 V.

### 9.2 Typical Application

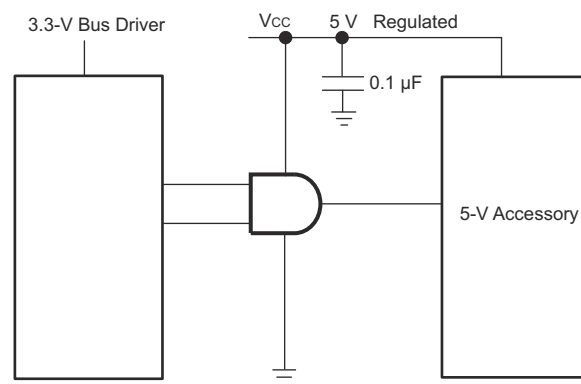


Figure 9-1. Typical Application Diagram

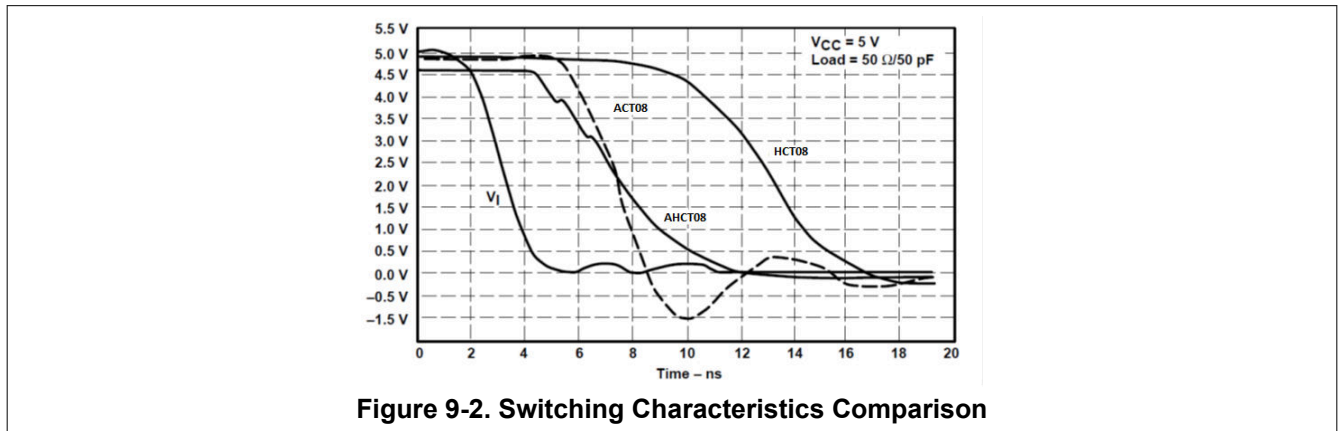
#### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 9.2.2 Detailed Design Procedure

- Recommended input conditions
  - Rise time and fall time specs: See  $(\Delta t/\Delta V)$  in the [Recommended Operating Conditions](#) table.
  - Specified High and low levels: See  $(V_{IH}$  and  $V_{IL})$  in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$
- Recommend output conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part
  - Outputs should not be pulled above  $V_{CC}$

### 9.2.3 Application Curves



### 9.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended. If there are multiple  $V_{CC}$  pins, 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

### 9.4 Layout

#### 9.4.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified in [Figure 9-3](#) are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ ; whichever makes more sense or is more convenient. It is generally acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the IOs, so they cannot float when disabled.

## 9.4.2 Layout Example

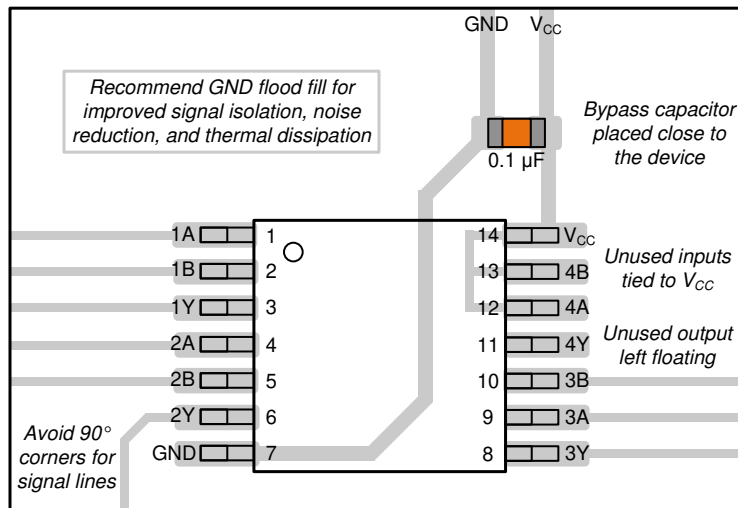


Figure 9-3. Example Layout for the SNx4AHCT08

## 10 Device and Documentation Support

### 10.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 10.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9682101Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101Q2A SNJ54AHCT08FK	<a href="#">Samples</a>
5962-9682101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101QCA SNJ54AHCT08J	<a href="#">Samples</a>
5962-9682101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101QDA SNJ54AHCT08W	<a href="#">Samples</a>
5962-9682101VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101VDA SNV54AHCT08W	<a href="#">Samples</a>
SN74AHCT08BQAR	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT08	<a href="#">Samples</a>
SN74AHCT08D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125	AHCT08	
SN74AHCT08DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB08	<a href="#">Samples</a>
SN74AHCT08DGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB08	<a href="#">Samples</a>
SN74AHCT08DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT08	<a href="#">Samples</a>
SN74AHCT08N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74AHCT08N	<a href="#">Samples</a>
SN74AHCT08NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT08	<a href="#">Samples</a>
SN74AHCT08PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	HB08	
SN74AHCT08PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	HB08	<a href="#">Samples</a>
SN74AHCT08PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB08	<a href="#">Samples</a>
SN74AHCT08RGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HB08	<a href="#">Samples</a>
SNJ54AHCT08FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101Q2A SNJ54AHCT08FK	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AHCT08J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101QC A SNJ54AHCT08J	<a href="#">Samples</a>
SNJ54AHCT08W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682101QD A SNJ54AHCT08W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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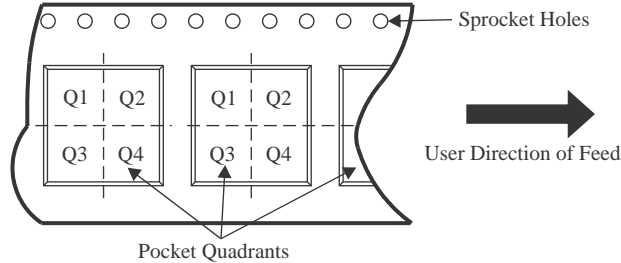
**OTHER QUALIFIED VERSIONS OF SN54AHCT08, SN54AHCT08-SP, SN74AHCT08 :**

- Catalog : [SN74AHCT08](#), [SN54AHCT08](#)
- Enhanced Product : [SN74AHCT08-EP](#), [SN74AHCT08-EP](#)
- Military : [SN54AHCT08](#)
- Space : [SN54AHCT08-SP](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT08BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AHCT08DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHCT08DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHCT08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT08NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHCT08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT08PWR	TSSOP	PW	14	2000	330.0	12.4	6.85	5.45	1.6	8.0	12.0	Q1
SN74AHCT08PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT08PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT08RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT08BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AHCT08DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AHCT08DGV	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74AHCT08DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AHCT08DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AHCT08NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74AHCT08PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHCT08PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AHCT08PWR	TSSOP	PW	14	2000	366.0	364.0	50.0
SN74AHCT08PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHCT08PWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AHCT08RGYR	VQFN	RGY	14	3000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9682101Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9682101QDA	W	CFP	14	25	506.98	26.16	6220	NA
5962-9682101VDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AHCT08N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHCT08N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AHCT08FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHCT08W	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/F 04/14

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

# DB0014A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\



J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW0014A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

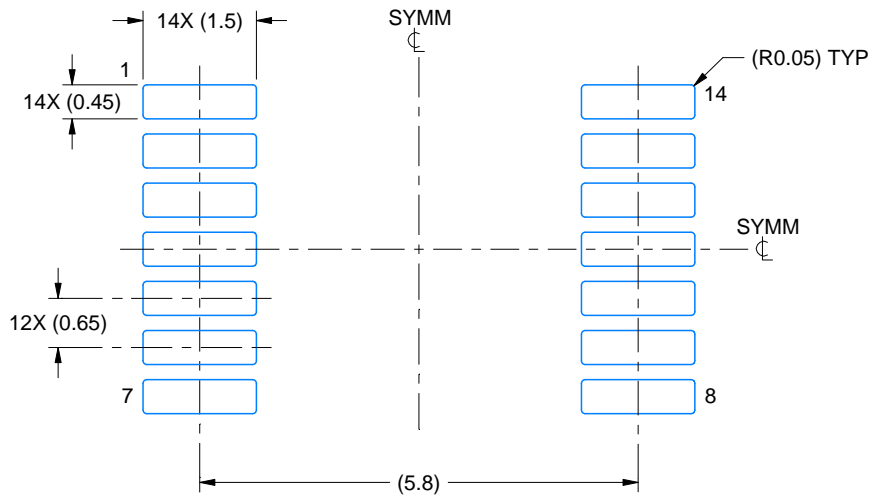
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

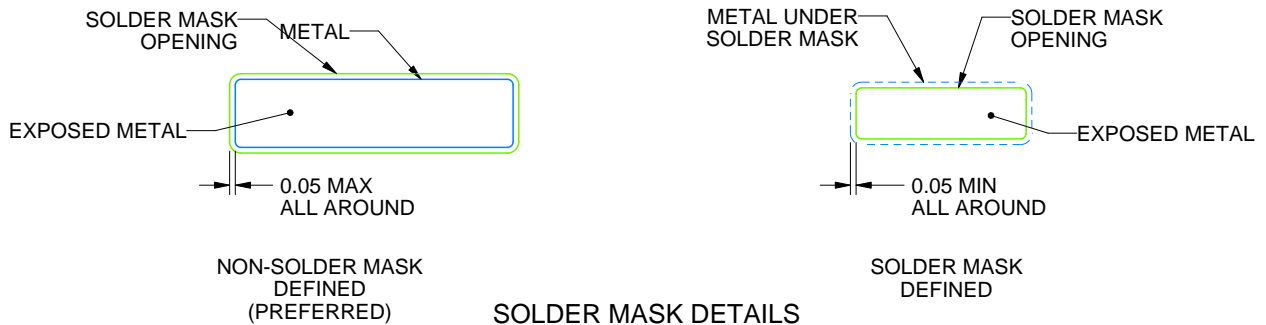
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

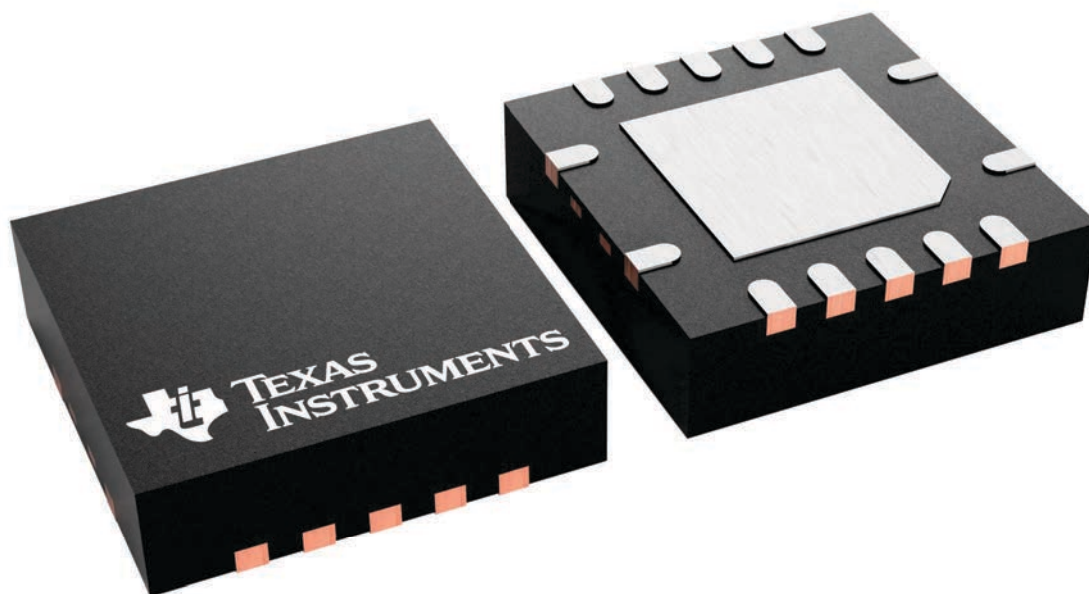
**RGY 14**

**VQFN - 1 mm max height**

3.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

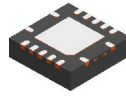
This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4231541/A



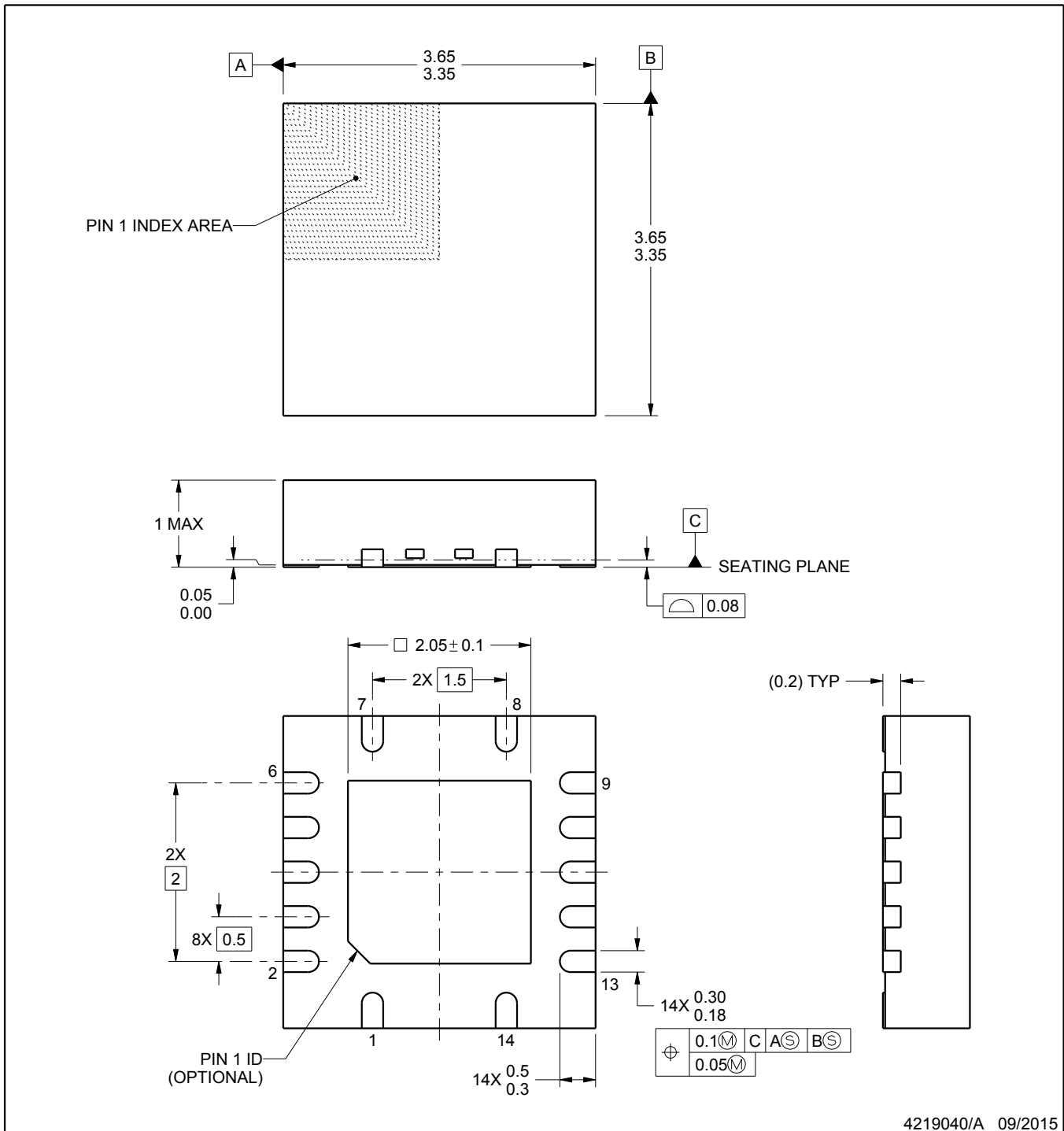
RGY0014A



PACKAGE OUTLINE

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4219040/A 09/2015

NOTES:

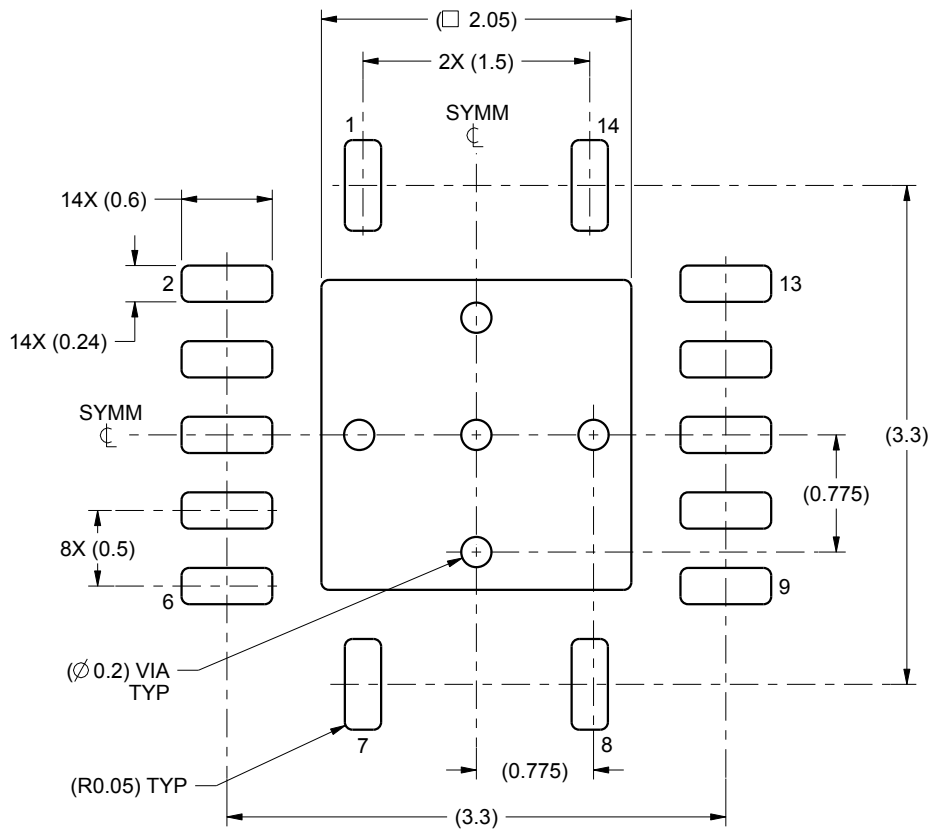
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

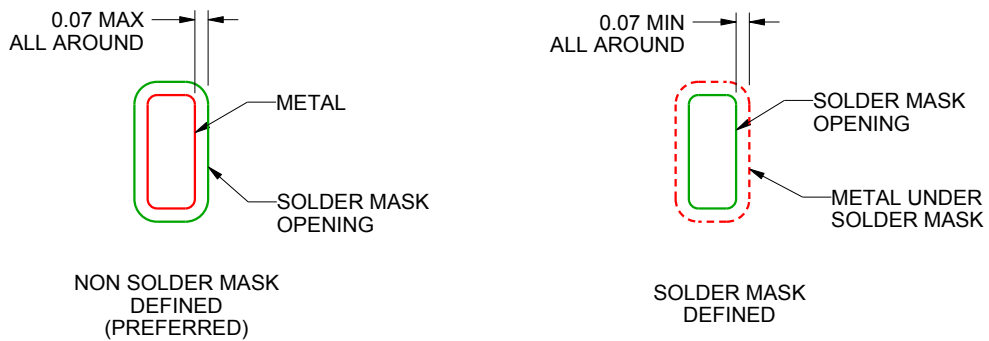
RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:20X



SOLDER MASK DETAILS

4219040/A 09/2015

NOTES: (continued)

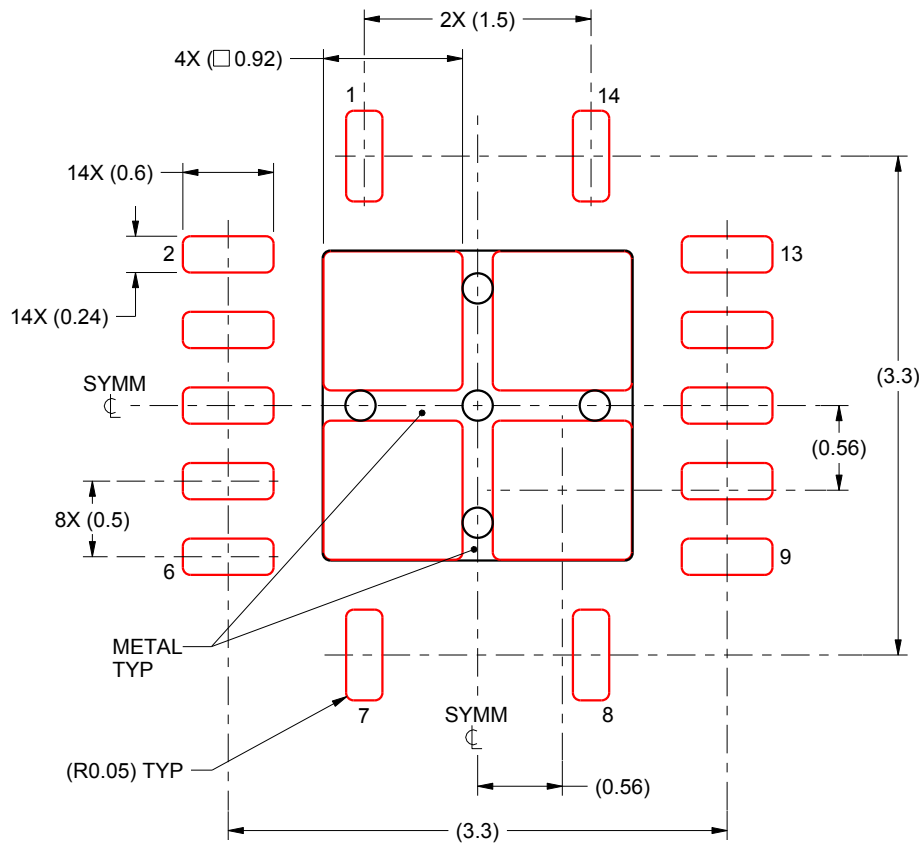
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
80% PRINTED SOLDER COVERAGE BY AREA  
SCALE:20X

4219040/A 09/2015

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**BQA 14**

**WQFN - 0.8 mm max height**

2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4227145/A





# EXAMPLE BOARD LAYOUT

WQFN - 0.8 mm max height

BQA0014A

PLASTIC QUAD FLAT PACK-NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



4224636/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
 88% PRINTED COVERAGE BY AREA  
 SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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